

# APTF1616SEJ3ZGGVBDC

1.6 x 1.6 mm Full-Color Surface Mount LED



### **DESCRIPTIONS**

- The Hyper Red device is based on light emitting diode chip made from AlGaInP
- The Green source color devices are made with InGaN on Sapphire Light Emitting Diode
- The Blue source color devices are made with InGaN Light Emitting Diode
- · Electrostatic discharge and power surge could damage the LEDs
- . It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs
- · All devices, equipments and machineries must be electrically grounded

## **FEATURES**

- 1.6 mm x 1.6 mm SMD LED, 0.7 mm thickness
- Low power consumption
- · Can produce any color in visible spectrum, including white light
- Package: 2000 pcs / reel
- Moisture sensitivity level: 3
- · Halogen-free
- RoHS compliant

### **APPLICATIONS**

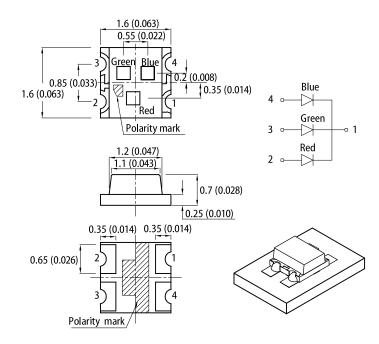
- Backlight
- · Status indicator
- · Home and smart appliances
- · Wearable and portable devices
- · Healthcare applications

### **ATTENTION**

Observe precautions for handling electrostatic discharge sensitive devices

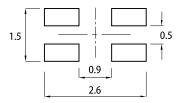


#### **PACKAGE DIMENSIONS**



#### RECOMMENDED SOLDERING PATTERN

(units: mm; tolerance: ± 0.1)



- 17. All dimensions are in millimeters (inches).
  2. Tolerance is ±0.2(0.008") unless otherwise noted.
  3. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.
- The device has a single mounting surface. The device must be mounted according to the specifications.

### **SELECTION GUIDE**

Part Number	Emitting Color (Material)	Lens Type	Iv (mcd) @ 20mA [2]		Viewing Angle [1]	
			Min.	Тур.	201/2	
APTF1616SEJ3ZGGVBDC	Hyper Red (AlGalnP)	Water Clear	200	360		
	Green (InGaN)		500	750	130°	
	■ Blue (InGaN)		80	140		

Notes.
1. 61/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
2. Luminous intensity / luminous flux: +/-15%.

3. Luminous intensity value is traceable to CIE127-2007 standards.



# ELECTRICAL / OPTICAL CHARACTERISTICS at T<sub>A</sub>=25°C

Parameter	Symbol	Emitting Color	Value		Unit
Farameter	Symbol	Emitting Color	Тур.	Max.	
Wavelength at Peak Emission I <sub>F</sub> = 20mA	Peak Emission $I_F$ = 20mA $$\lambda_{peak}$$ Green Blue		640 520 465	-	nm
Dominant Wavelength I <sub>F</sub> = 20mA	λ <sub>dom</sub> <sup>[1]</sup>	Hyper Red Green Blue	625 525 470	-	nm
Spectral Bandwidth at 50% $\Phi$ REL MAX I <sub>F</sub> = 20mA	Δλ	Hyper Red Green Blue	25 35 22	-	nm
Capacitance	С	Hyper Red Green Blue	27 100 100	-	pF
Forward Voltage I <sub>F</sub> = 20mA	V <sub>F</sub> <sup>[2]</sup>	Hyper Red Green Blue	2.2 3.2 3.3	2.8 4 4	V
Reverse Current (V <sub>R</sub> = 5V)	I <sub>R</sub>	Hyper Red Green Blue	-	10 50 50	μΑ
Temperature Coefficient of $\lambda_{peak}$ $I_F$ = 20mA, -10°C $\leq$ T $\leq$ 85°C	$TC_{\lambda peak}$	Hyper Red Green Blue	0.13 0.05 0.04	-	nm/°C
Temperature Coefficient of $\lambda_{dom}$ $I_F$ = 20mA, -10°C $\leq T \leq 85^{\circ}C$	$TC_{\lambdadom}$	Hyper Red Green Blue	0.06 0.03 0.03	-	nm/°C
Temperature Coefficient of $V_F$ $I_F$ = 20mA, -10°C $\leq$ T $\leq$ 85°C	TC <sub>V</sub>	Hyper Red Green Blue	-2 -3 -3	-	mV/°C

# ABSOLUTE MAXIMUM RATINGS at T<sub>A</sub>=25°C

Barranton	Symbol	Value			11-24
Parameter		Hyper Red	Green	Blue	Unit
Power Dissipation	P <sub>D</sub> <sup>[1]</sup>	84	120	120	mW
Reverse Voltage	$V_R$	5	5	5	V
Junction Temperature	T <sub>j</sub>	115	115	115	°C
Operating Temperature	T <sub>op</sub>	-40 to +85			°C
Storage Temperature	T <sub>stg</sub>	-40 to +85			°C
DC Forward Current	I <sub>F</sub> <sup>[1]</sup>	30	30	30	mA
Peak Forward Current	I <sub>FM</sub> <sup>[2]</sup>	150	100	100	mA
Electrostatic Discharge Threshold (HBM)	-	3000	450	250	V
Thermal Resistance (Junction / Ambient)	R <sub>th JA</sub> <sup>[2]</sup>	600	700	690	°C/W
Thermal Resistance (Junction / Solder point)	R <sub>th JS</sub> <sup>[2]</sup>	500	590	580	°C/W

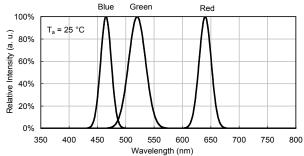
The dominant wavelength (λd) above is the setup value of the sorting machine. (Tolerance λd: ±1nm.)
 Forward voltage: ±0.1V.
 Wavelength value is traceable to CIE127-2007 standards.
 Excess driving current and / or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

Notes:
1. 1/1/0 Duty Cycle, 0.1ms Pulse Width.
2. R<sub>th. Jh.</sub> Results from mounting on PC board FR4 (pad size ≥ 16 mm² per pad).
3. Relative humidity levels maintained between 40% and 60% in production area are recommended to avoid the build-up of static electricity – Ref JEDEC/JESD625-A and JEDEC/J-STD-033.

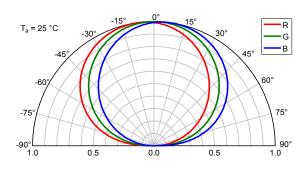


### **TECHNICAL DATA**

## **RELATIVE INTENSITY vs. WAVELENGTH**

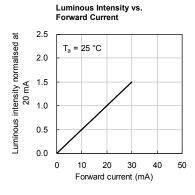


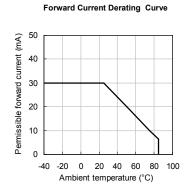
## **SPATIAL DISTRIBUTION**

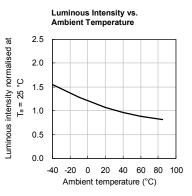


### **HYPER RED**

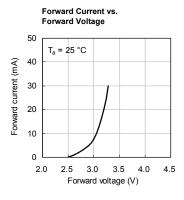
Forward Current vs. Forward Voltage  $T_a = 25$  °C Forward current (mA) 40 30 20 10 0 2.5 1.5 1.7 1.9 2.1 2.3 Forward voltage (V)

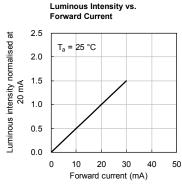


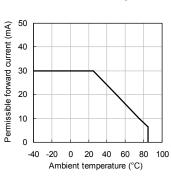




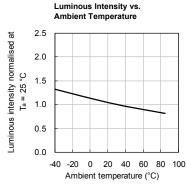
#### **GREEN**





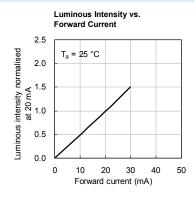


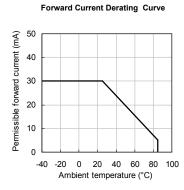
Forward Current Derating Curve

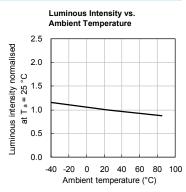


# **BLUE**

Forward Current vs. Forward Voltage 50  $T_a = 25 \,^{\circ}C$ 40 Forward current (mA) 30 20 10 2.0 2.8 3.2 3.6 4.0 Forward voltage (V)







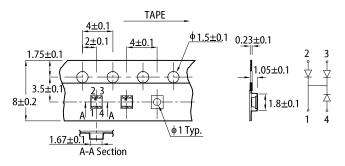


#### REFLOW SOLDERING PROFILE for LEAD-FREE SMD PROCESS

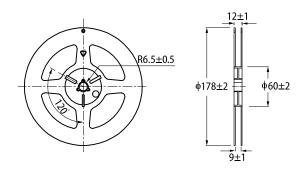
#### 300 above 255°C (°C) 260°C max. 30s max. 10s max. 250 3°C/s max. 6°C/s max. 200 150 Temperature pre-heating 100 150~200°C above 217°C 60~120s 60~150s 50 . 25℃ 150 200 250 0 50 100 300 (sec) Time -

- 1. Don't cause stress to the LEDs while it is exposed to high temperature.
  2. The maximum number of reflow soldering passes is 2 times.
  3. Reflow soldering is recommended. Other soldering methods are not recommended as they might cause damage to the product.

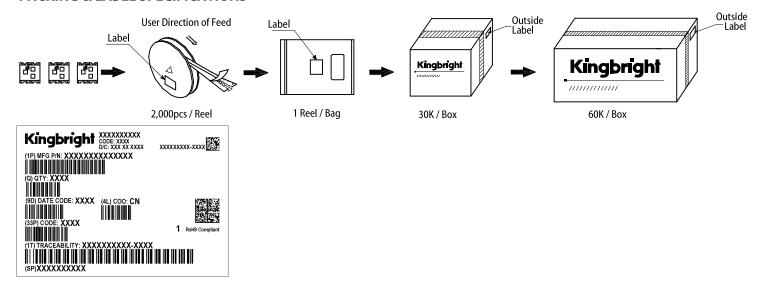
#### TAPE SPECIFICATIONS (units: mm)



#### **REEL DIMENSION** (units: mm)



## **PACKING & LABEL SPECIFICATIONS**



#### **PRECAUTIONARY NOTES**

- The information included in this document reflects representative usage scenarios and is intended for technical reference only
- The part number, type, and specifications mentioned in this document are subject to future change and improvement without notice. Before production usage customer should refer to the latest datasheet for the updated specifications.
- When using the products referenced in this document, please make sure the product is being operated within the environmental and electrical limits specified in the datasheet. If customer usage exceeds the specified limits, Kingbright will not be responsible for any subsequent issues.

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